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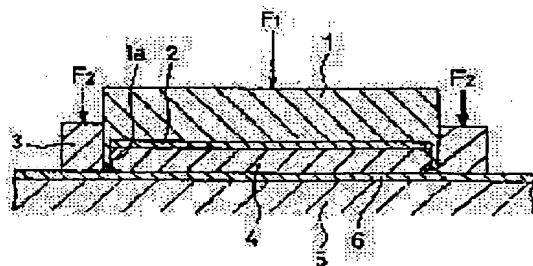
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(54) POLISHING DEVICE AND POLISHING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a polishing device and a polishing method capable of preventing the occurrence of the excess and deficiency of a polishing amount around the periphery of a polishing object, and performing a polishing process at a higher degree of flatness by causing a presser ring to apply an optimum pressing force to an abrasive cloth, depending on the polishing object or a polishing condition.

SOLUTION: A polishing device is equipped with a turntable 5 having an abrasive cloth 6 pasted to the upper surface, and a top ring 1, and holds a semiconductor wafer 4 between the turntable 5 and the top ring 1 in such a state as pressed at the prescribed force. The semiconductor wafer 4 is thereby polished, flattened and finished to mirror surface. Regarding the polishing device so formed, a presser ring 3 is provided around the top ring 1 having a recess for housing the semiconductor wafer 4 in such a state as freely movable in a vertical direction, and a presser means is provided for pressing the presser ring 3 to the abrasive cloth 6. Also, the pressing force of the pressing means is made variable.



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